

BY TELEFAX TO: (703) 872-9311
EXPEDITED PROCEDURE
RESPONSE UNDER 37 CFR 1.116
EXAMINING GROUP: 1700
BOX AF

DOCKET NO.: 4029

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
IN THE MATTER OF THE APPLICATION FOR PATENT

OF: Michio OSADA et al.

| Art Unit: 1722

SERIAL NO.: 09/705,237

| Confirmation No.: 4586

FILED: November 2, 2000

| EX.: Thukhanh T. Nguyen

FOR: Die Used for Resin-Sealing and
Molding an Electronic Component.

MS AF
COMMISSIONER FOR PATENTS
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450

May 30, 2003

RESPONSE TO THE FINAL OFFICE ACTION OF APRIL 1, 2003 INCLUDING
AN ATTACHED COVER SHEET WITH CERTIFICATE OF TELEFAX TRANSMISSION

Dear Sir:

This Response should receive expedited handling, as it is being
filed **within two months** after the date of the Final Action.

Please amend the above identified application as follows.

(THIS AMENDMENT IS IN THE NEW REVISED AMENDMENT FORMAT, WITH
DELETED MATTER SHOWN BY STRIKETHROUGH AND ADDED MATTER SHOWN BY
UNDERLINING. A SEPARATE MARKED-UP VERSION IS THUS NOT REQUIRED).

4029/WFF:ar

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